

2SA0886 (2SA886)

Silicon PNP epitaxial planar type

For low-frequency power amplification
Complementary to 2SC1847

■ Features

- Output of 4 W can be obtained by a complementary pair with 2SC1847
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-50	V
Collector to emitter voltage	V_{CEO}	-40	V
Emitter to base voltage	V_{EBO}	-5	V
Peak collector current	I_{CP}	-3	A
Collector current	I_C	-1.5	A
Collector power dissipation	P_C	1.2 *1	W
		5 *2	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Without heat sink

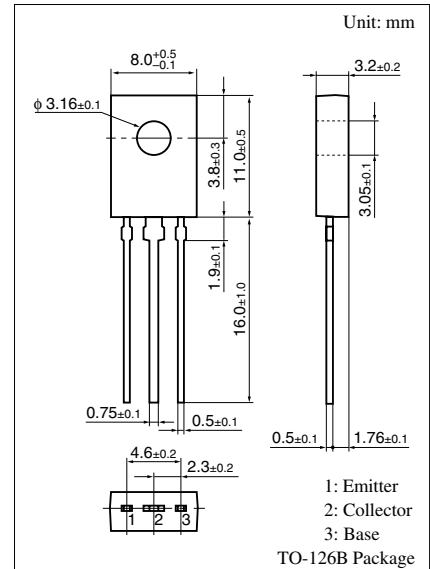
*2: With a $100 \times 100 \times 2$ mm A1 heat sink

■ Electrical Characteristics $T_C = 25^\circ\text{C}$

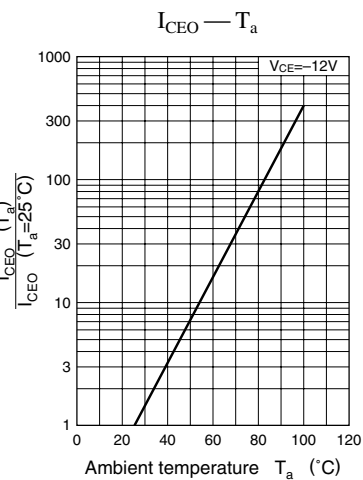
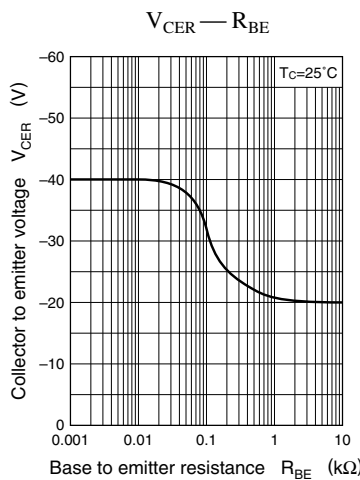
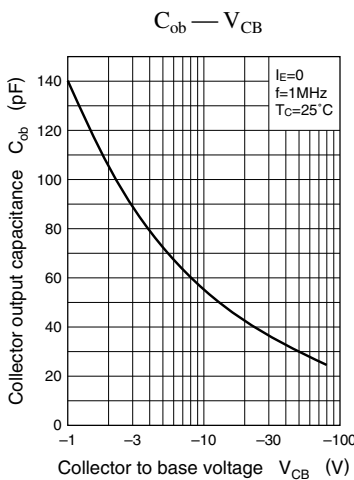
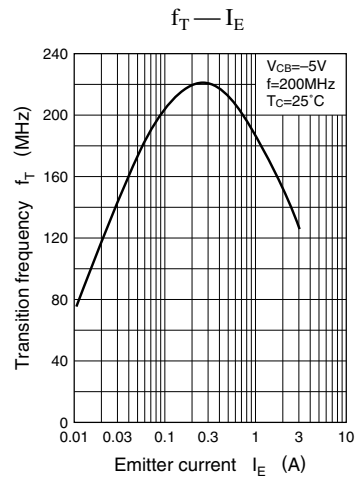
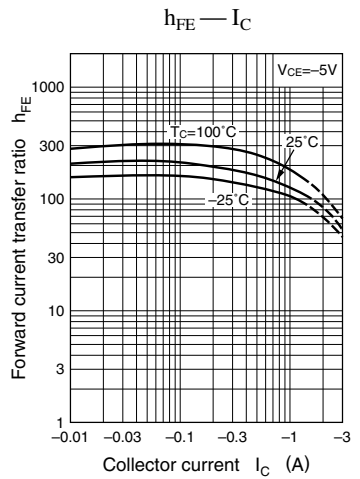
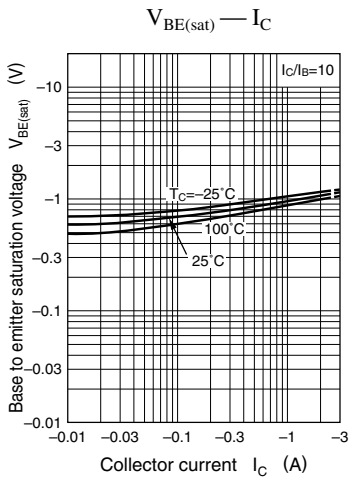
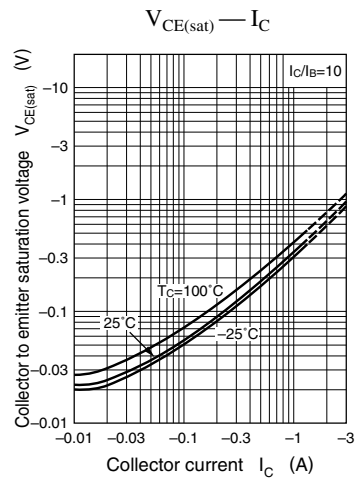
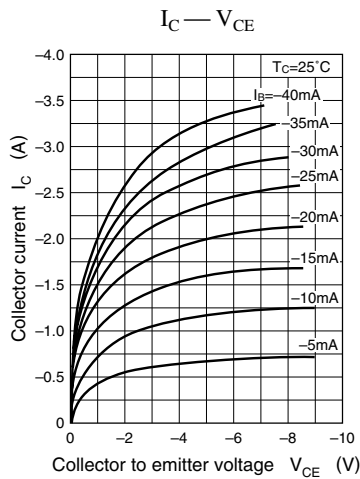
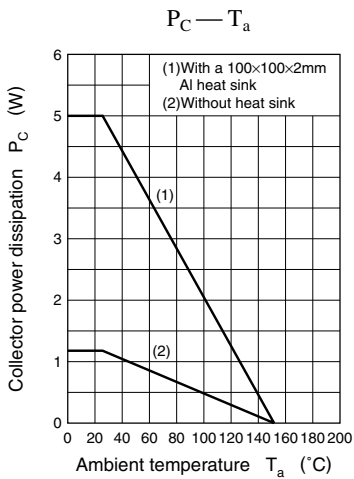
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -20$ V, $I_E = 0$			-1	μA
	I_{CEO}	$V_{CE} = -10$ V, $I_B = 0$			-100	μA
Emitter cutoff current	I_{EBO}	$V_{EB} = -5$ V, $I_C = 0$			-10	μA
Collector to base voltage	V_{CBO}	$I_C = -1$ mA, $I_E = 0$	-50			V
Collector to emitter voltage	V_{CEO}	$I_C = -2$ mA, $I_B = 0$	-40			V
Forward current transfer ratio *	h_{FE}	$V_{CE} = -5$ V, $I_C = -1$ A	80		220	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -1.5$ A, $I_B = -0.15$ A			-1.0	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = -2$ A, $I_B = -0.2$ A			-1.5	V
Transition frequency	f_T	$V_{CB} = -5$ V, $I_E = 0.5$ A, $f = 200$ MHz		150		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -20$ V, $I_E = 0$, $f = 1$ MHz		45		pF

Note) *: Rank classification

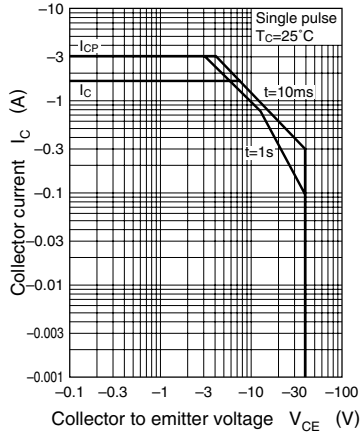
Rank	Q	R
h_{FE}	80 to 160	120 to 220



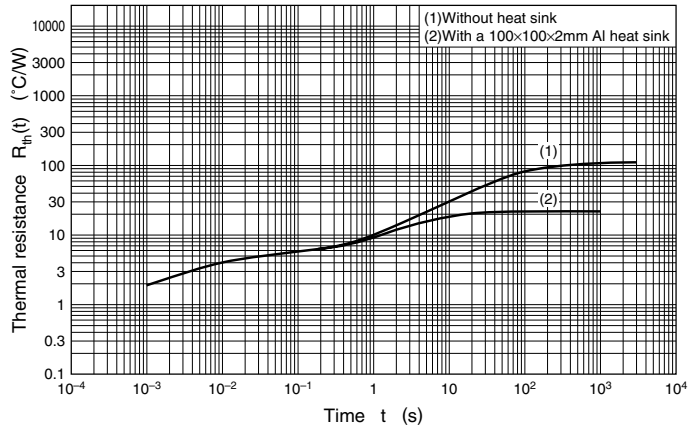
Note.) The Part number in the Parenthesis shows conventional part number.



Area of safe operation (ASO)



$R_{th(t)} - t$



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